| L Number | Hits | Search Text | DB | Time stamp |
|---|---|---|---|---|
| – | 48 | (ceramic adj substrate) and ((thermosetting and inorganic) with (filler or underfill)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/21 22:46 |
| – | 37 | (ceramic adj substrate) and ((epoxy and inorganic) with (filler or underfill)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 11:52 |
| – | 27 | ((ceramic adj substrate) and ((thermosetting and inorganic) with (filler or underfill)) ) not ((ceramic adj substrate) and ((epoxy and inorganic) with (filler or underfill)) ) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/24 00:03 |
| – | 0 | (ceramic adj substrate) and (((epoxy or thermosetting) and inorganic) with (capsulant)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/24 00:26 |
| – | 0 | (ceramic adj substrate) and (((epoxy or thermosetting) and inorganic) with (capsulent)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/24 00:26 |
| – | 0 | (ceramic adj board) and (((epoxy or thermosetting) and inorganic) with (capsulant)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/24 00:26 |
| – | 4 | (ceramic adj board) and (((epoxy or thermosetting) and inorganic) with (fill or underfill)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/24 01:20 |
| – | 1 | ("6356453").PN. | USPAT | 2003/03/24 01:32 |
| – | 1 | ("20010030059").PN. | USPAT; US-PGPUB | 2003/03/24 01:32 |
| – | 1 | ("20020096759").PN. | USPAT; US-PGPUB | 2003/10/07 13:32 |
| – | 1 | ("5831833").PN. | USPAT; US-PGPUB | 2003/10/07 13:32 |
| – | 535 | ((ceramic or glass adj epoxy) near3 substrate) and ((epoxy and inorganic) with (filler or underfill or resin)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 16:55 |
| – | 127 | (((ceramic or glass adj epoxy) near3 substrate) and ((epoxy and inorganic) with (filler or underfill or resin)) ) and (semiconductor and (resistor or capacitor or passive)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/07 16:18 |
| – | 0 | ((((ceramic or glass adj epoxy) near3 substrate) and ((epoxy and inorganic) with (filler or underfill or resin)) ) and (semiconductor and (resistor or capacitor or passive))) not (((ceramic or glass adj epoxy) near3 substrate) and ((epoxy and inorganic) with (filler or underfill or resin)) ) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/07 15:15 |
| – | 408 | (((ceramic or glass adj epoxy) near3 substrate) and ((epoxy and inorganic) with (filler or underfill or resin)) ) not ((((ceramic or glass adj epoxy) near3 substrate) and ((epoxy and inorganic) with (filler or underfill or resin)) ) and (semiconductor and (resistor or capacitor or passive))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/07 15:15 |

| - | 4406 | ((ceramic or glass adj epoxy) near3 substrate) and (epoxy with (filler or underfill or resin)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/21 22:49 |
|---|------|-----|-----|-----|
| - | 852 | (((ceramic or glass adj epoxy) near3 substrate) and (epoxy with (filler or underfill or resin)) ) and (semiconductor and (resistor or capacitor or passive)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/07 16:18 |
| - | 725 | ((((ceramic or glass adj epoxy) near3 substrate) and (epoxy with (filler or underfill or resin)) ) and (semiconductor and (resistor or capacitor or passive))) not (((ceramic or glass adj epoxy) near3 substrate) and ((epoxy and inorganic) with (filler or underfill or resin)) ) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/07 16:34 |
| - | 629 | 257/728.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 17:12 |
| - | 351 | 257/729.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/16 17:41 |
| - | 1767 | 257/678.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/16 17:41 |
| - | 640 | 257/687.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/16 17:41 |
| - | 1394 | 257/690.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/16 17:41 |
| - | 961 | 257/691.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/16 17:41 |
| - | 1341 | 257/700.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 15:30 |
| - | 641 | 257/703.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/16 17:41 |
| - | 1056 | 257/701.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/16 17:41 |
| - | 465 | 257/705.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/16 17:41 |
| - | 1 | ("6587008").PN. | USPAT | 2004/03/30 15:28 |
| - | 0 | ("US-5795799-$.DID.").PN. | USPAT | 2004/05/07 11:25 |
| - | 1 | US-5795799-$.DID. | USPAT | 2004/05/07 11:25 |

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| – | 286 | ((glass adj epoxy) near3 substrate) and ((epoxy and inorganic) same (filler or underfill or resin)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 16:56 |
| – | 715 | (ceramic near3 substrate) and ((epoxy and inorganic) SAME (filler or underfill or resin)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 16:57 |
| – | 145 | (((glass adj epoxy) near3 substrate) and ((epoxy and inorganic) same (filler or underfill or resin)) ) not ((ceramic near3 substrate) and ((epoxy and inorganic) SAME (filler or underfill or resin)) ) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 16:57 |
| – | 678 | 257/687.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 17:12 |
| – | 1467 | 257/690.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 17:12 |
| – | 1040 | 257/691.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 17:12 |
| – | 1417 | 257/700.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 17:13 |
| – | 662 | 257/703.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 17:13 |
| – | 1110 | 257/701.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 17:13 |
| – | 475 | 257/705.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 17:13 |
| – | 674 | 257/728.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 17:13 |
| – | 360 | 257/729.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 17:31 |
| – | 1938 | 257/678.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/07 18:23 |
| – | 74 | (ceramic adj substrate) and ((thermosetting and inorganic) with (filler or underfill)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/10 11:48 |
| – | 1 | ("6163456").PN. | USPAT | 2004/07/22 15:18 |

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| – | 4821 | ((ceramic or (glass adj epoxy)) near3 substrate) and (epoxy near5 (filler or underfill or resin)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/21 22:49 |
| – | 142 | (((ceramic or (glass adj epoxy)) near3 substrate) and (epoxy near5 (filler or underfill or resin)) ) and (epoxy near5 inorganic) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 12:59 |
| – | 1 | "2000397728" | JPO; DERWENT | 2004/07/22 12:26 |
| – | 1 | "6160526".PN. | USPAT | 2004/07/22 12:31 |
| – | 1 | "6060150".PN. | USPAT | 2004/07/22 12:31 |
| – | 1 | "6038133".PN. | USPAT | 2004/07/22 12:32 |
| – | 1 | "5172304".PN. | USPAT | 2004/07/22 12:32 |
| – | 293 | (((ceramic or (glass adj epoxy)) near3 substrate) and (epoxy near5 (filler or underfill or resin)) ) and (epoxy with inorganic) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 12:58 |
| – | 150 | ((((ceramic or (glass adj epoxy)) near3 substrate) and (epoxy near5 (filler or underfill or resin)) ) and (epoxy with inorganic) ) not (((((ceramic or (glass adj epoxy)) near3 substrate) and (epoxy near5 (filler or underfill or resin)) ) and (epoxy near5 inorganic) ) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 13:00 |
| – | 143 | (((ceramic or (glass adj epoxy)) near3 substrate) and (epoxy near5 (filler or underfill or resin)) ) and (epoxy near5 inorganic) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 15:27 |
| – | 1 | ("5795799").PN. | USPAT | 2004/07/22 15:19 |
| – | 1 | ("5831833").PN. | USPAT | 2004/07/22 15:21 |
| – | 1 | ("20020096759").PN. | USPAT; US-PGPUB | 2004/07/22 15:22 |
| – | 2 | ((alo or (aluminum adj oxide) or beo) near3 substrate) and (epoxy near5 (filler or underfill or resin)) and (epoxy near5 inorganic) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 15:30 |
| – | 0 | 257/701..ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 15:31 |
| – | 1132 | 257/701.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 15:31 |
| – | 667 | 257/703.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 15:31 |
| – | 478 | 257/705.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 15:31 |
| – | 692 | 257/728.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 15:31 |
| – | 372 | 257/729.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 15:31 |

| - | 2014 | 257/678.ccls. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/07/22 15:32 |
|---|------|---------------|------|------------------|
| - | 692 | 257/687.ccls. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/07/22 15:32 |
| - | 1494 | 257/690.ccls. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/07/22 15:32 |
| - | 1083 | 257/691.ccls. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/07/22 15:32 |
| - | 1448 | 257/700.ccls. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/07/22 15:34 |